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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Taran, et al. /
Appl. No. : 09/830,634 /
Filed : April 27, 2001 /
For : MULTILAYERED CONNECTION PLATE /
Examiner : Norris, J.

) Group Art Unit 2827

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

June 17, 200
(Date)

John M. Carson, Reg. No. 34,303

AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed Feb. 15, 2002, please amend the above identified application as shown in the accompanying pages.

IN THE ABSTRACT

Please cancel the Abstract.

Please insert therefor a new Abstract as follows:

A multilayered switching structure is disclosed for the development and the production of an apparatus based on microelectronic components and semiconductor devices. The structure may widely be used in the production of multilayered printed circuit cards and switching structures for monocrystalline modules. The multilayered switching structure includes a plurality of layers of a dielectric material which include electroconductive tracks on their surfaces and which consist of switching layers. This structure also includes contact nodes consisting of metallized contacts which are aligned with each other and which are electrically and mechanically connected together by an electroconductive binding material. The contact nodes

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